

# **Product Change Notification / CADA-02KPFT899**

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21-Dec-2022

# **Product Category:**

Clock and Timing - Clock and Data Distribution

# **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 5046 Final Notice: Qualification of G700LA as a new mold compound material for selected MAX24x8x device family available in 68L WQFN (8x8x0.8mm) package assembled at ASCL assembly site

### **Affected CPNs:**

CADA-02KPFT899\_Affected\_CPN\_12212022.pdf CADA-02KPFT899\_Affected\_CPN\_12212022.csv

#### **Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of G700LA as a new mold compound material for selected MAX24x8x device family available in 68L WQFN (8x8x0.8mm) package assembled at ASCL assembly site

#### **Pre and Post Change Summary:**

Assembly Site	ASE Group Chung-Li	ASE Group Chung-Li			
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Wire Material	PdCu/ Cu	PdCu/ Cu			
Die Attach Material	EN-4900GC	EN-4900GC			
Molding Compound Material	CEL-9240HF10AC	G700LA			
Lead-Frame Material	C194	C194			

#### Impacts to Data Sheet:None

Change ImpactNone

**Reason for Change:**To improve manufacturability by qualifying G700LA as a new molding compound material.

**Change Implementation Status:**In Progress

Estimated First Ship Date: January 20,2023 (date code: 2303)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

# Time Table Summary:

	April 2022			>	December 2022				January 2023							
Workweek	1 4	1 5	1 6	1 7	1 8		4 9	5 0	5 1	5 2	5 3	1	2	3	4	5
Initial PCN Issue Date		Х														
Qual Report Availability										Х						
Final PCN Issue Date										Х						
Estimated Implementation Date														х		

Method to Identify Change: Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** April 5, 2022: Issued initial notification.

December 21, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on January 20, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachments:

PCN\_CADA-02KPFT899 Qual\_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MAX24188ETK2

MAX24188ETK2T

MAX24287ETK2

MAX24287ETK2T

MAX24288ETK2

MAX24288ETK2T